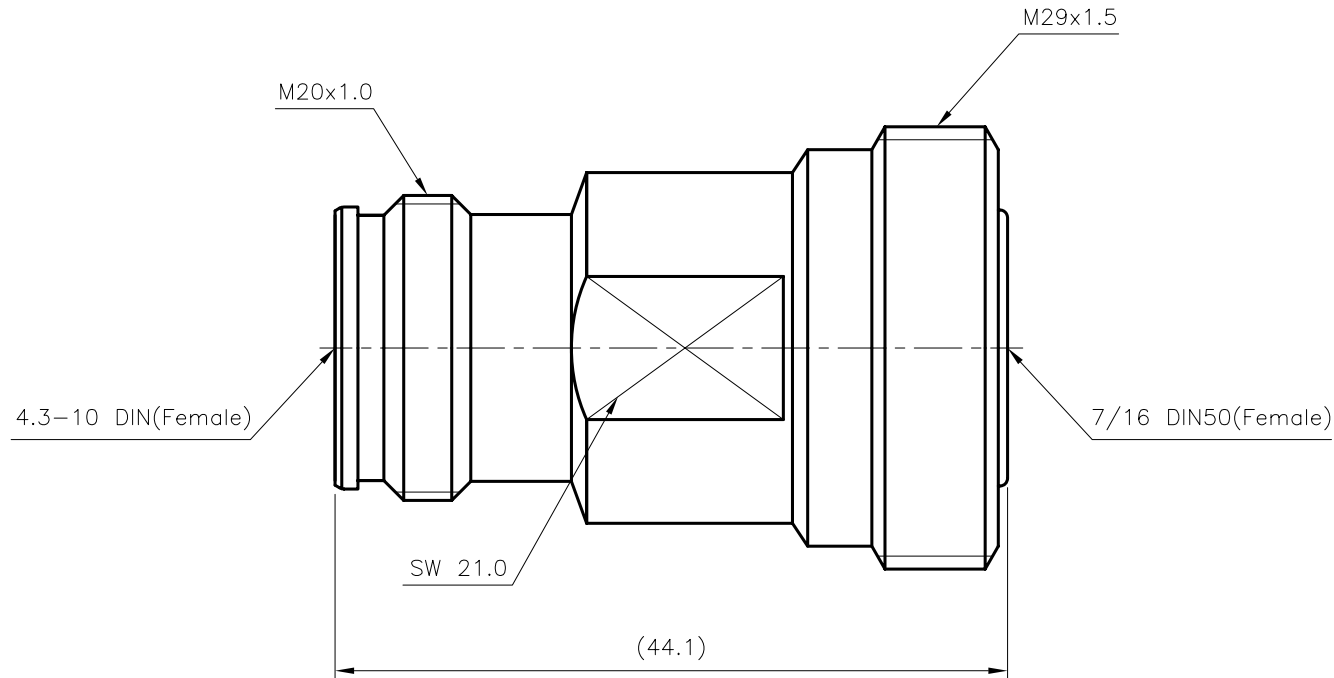


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2016.06.03.
1	[설번처리No.201703-0006] PIN , JACK 상대물 탠션 고려 수정	I.C.KIM		2017.03.10.



ELECTRICAL DATA :

1. IMPEDANCE : 50ohm
2. FREQUENCY RANGE : DC~3GHz
3. VSWR (Max) : 1.2
4. INSERTION LOSS : 0.2dB (Max)
5. PIMD (-43dBm / 2tone) 3rd Order IMD : -160dBc (Min)

조립순서

1. 2번 PIN +4번 절연체 조립
2. 3번 PIN +5번 절연체 조립
3. 2번 + 3번 PIN 억지끼움 후 납땜 작업
4. 1번 BODY에 6번 JACK 억지끼움 작업
5. 정해진 JIG로 3번 PIN과 5번 절연체 동시에 눌러서 조립

6	JACK	1	MBsBD C3604BD-F	Silver Plate (3 μ m)	DJA00228-5/6 DJA00228-5/3
5	INSULATOR	1	TEFLON		DIN02777-N/1
4	INSULATOR	1	TEFLON		DIN02776-N/1
3	CONTACT	1	MBsBD C3601BD	Silver Plate (5 μ m)	DCT03703-5/1
2	CONTACT	1	BeCu C17300	Silver Plate (5 μ m)	DCT03702-5/1
1	BODY	1	MBsBD C3604BD-F	SUCO Plate (3 μ m)	DAD00315-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2017. 03. 10.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY		
MATERIAL	_____	CHECKED BY		KJ COMTECH CO.,LTD. TITLE 4.3/10 DIN50 (J) 7/16 DIN50(J) ADAPTOR
		DRAWN BY	I.C.KIM	
FINISH	_____	SCALE	2/1	A4 DWG NO. AD00584-7/1 REVISION 1 SHEET 1 of 1
		UNIT	mm	